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Substitute for form 1449/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)				Complete if known	
Sheet	1	of	2	Application Number	10/665,757
				Filing Date	September 19, 2003
				First Named Inventor	Glenn J. Leedy
				Art Unit	2822
				Examiner Name	Pamela E. Perkins
				Attorney Docket Number	ELM-1 CONT.9

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Documents	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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		Country Code ¹ - Number ² - Kind Code ³				
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Sheet	2	of	2	Attorney Docket Number	ELM-1 CONT.9

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Examiner Signature		Date Considered	4/28/00
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All References Have Been Considered:

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